A B S T R A C T

The invention provides a method of fabricating substrates, in particular for optics, electronics, or optoelectronics. The method comprises the following steps:

· transferring a seed layer (2) onto a support (12) by molecular adhesion in an adhesion interface;

· growing a working layer (16) epitaxially on the seed layer; and

· applying stresses to cause the assembly constituted by the seed layer (2) and the working layer (16) to become detached from the support (12) at the adhesion interface.



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